

DATA SHEET

LOW OHMIC CHIP RESISTORS

RL series

5%, 2%, 1%

sizes 0402/0603/0805/1206/

1210/1218/2010/2512

RoHS compliant & Halogen Free



TESTS AND REQUIREMENTS
Table 4 Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Life/ Endurance	IEC 60115-1 4.25.1 MIL-STD-202 Method 108A	1,000 hours at 70±2°C applied RCWV 1.5 hours on, 0.5 hour off, still air required	±(2% +0.5mΩ)
High Temperature Exposure	IEC 60068-2-2	1,000 hours at maximum operating temperature depending on specification, unpowered No direct impingement of forced air to the parts Normal power : Tolerances: 155±5°C Double power : Tolerances: 125±5°C	±(1% +0.5mΩ)
Moisture Resistance	MIL-STD-202 Method 106G	Each temperature / humidity cycle is defined at 8 hours, 3 cycles / 24 hours for 10d with 25 °C / 65 °C 95% R.H, without steps 7a & 7b, unpowered Parts mounted on test-boards, without condensation on parts	±(2% +0.5mΩ)
Thermal Shock	MIL-STD-202 Method 107G	-55/+125 °C Number of cycles required is 300. Devices mounted Maximum transfer time is 20 seconds. Dwell time is 15 minutes.	±(1% +0.5mΩ)
Short time overload	IEC60115-1 4.13	RL standard power: 2.5 times rated voltage for 5 sec at room temperature RL high power: 5 times rated power for 5 sec at room temperature	±(2% +0.5mΩ) No visible damage
Board Flex/ Bending	IEC 60115-1 4.33	Device mounted on PCB test board as described, only 1 board bending required 3 mm bending Bending time: 60±5 seconds Ohmic value checked during bending	±(1% +0.5mΩ) No visible damage

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Solderability - Wetting	J-STD-002 test B	Electrical Test not required Magnification 50X SMD conditions: 1 st step: method B, aging 4 hours at 155 °C dry heat 2 nd step: leadfree solder bath at 245±3 °C Dipping time: 3±0.5 seconds	Well tinned (≥95% covered) No visible damage
- Leaching	J-STD-002 test D	Leadfree solder, 260 °C, 30 seconds immersion time	No visible damage
- Resistance to Soldering Heat	IEC 60115-1 4.18	Condition B, no pre-heat of samples. Leadfree solder, 260 °C, 10 seconds immersion time Procedure 2 for SMD: devices fluxed and cleaned with isopropanol	±(1% +0.5mΩ) No visible damage

REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	May 31, 2017	-	- Add 10" packing
Version 1	Dec. 16, 2015	-	- Extend 0805 T.C.R. range
Version 0	Nov. 11, 2014	-	- First issue of this specification

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